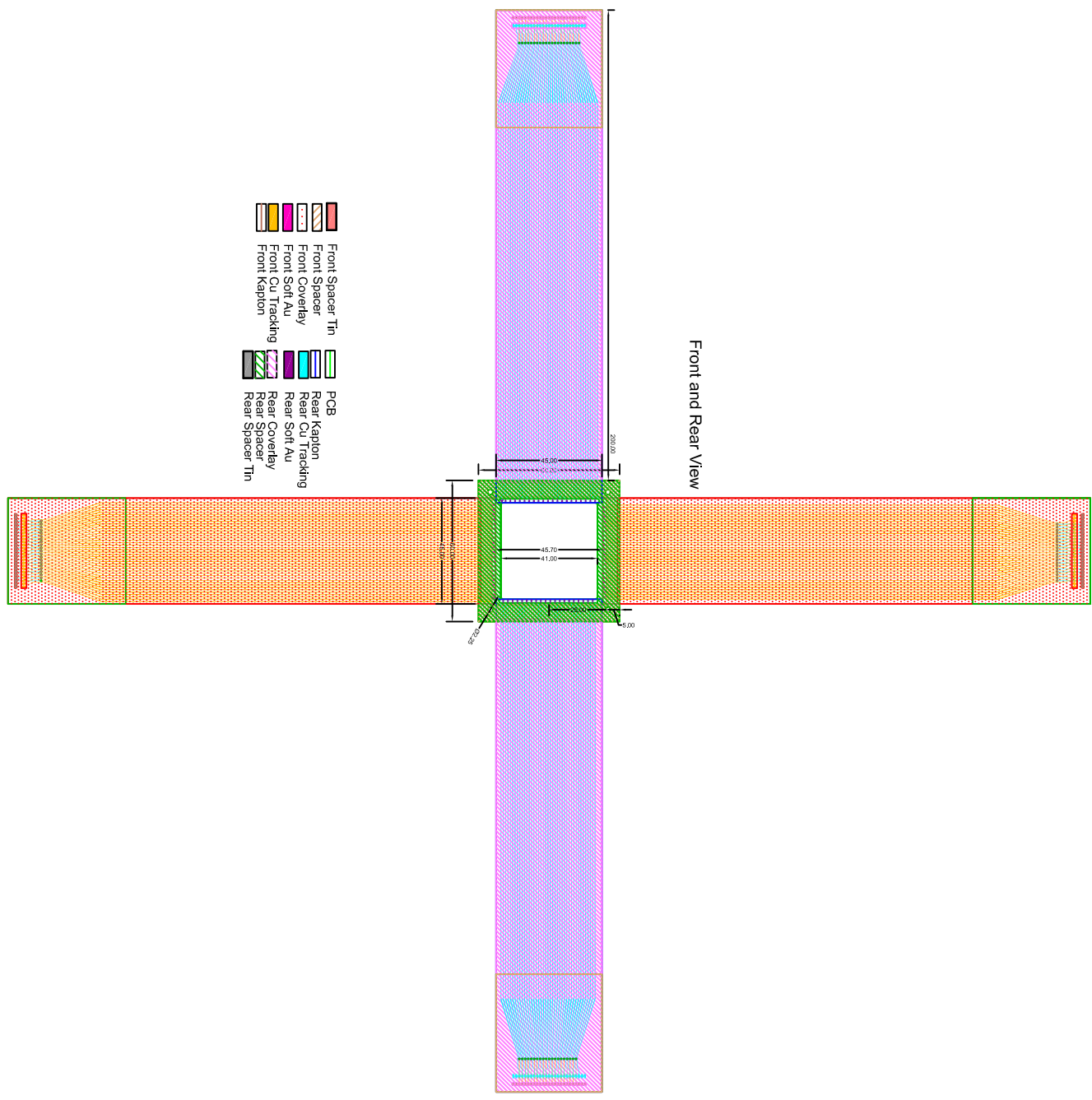


Drawn, Design Approved	Checked	Date
N.W	S.W	15/06/2010

Tolerances Unless Stated		Material - ~3.1 mm total thick FR4 PCB material.	
Package O/D ± 0.1mm	Plating - 1oz soft Au suitable for wire bonding on PCB with rolled annealed Cu on Kapton	Front Spacer	FR4
Package Hole Ø ± 0.05mm	Front Spacer- 0.6 mm FR4	Front Coverlay	FR4
Package Hole Pos'n ± 0.1mm	Rear Spacer- 0.6 mm FR4	Front Soft Au	FR4
Material Thickness ± 10 %	Ledge - 1.55 mm deep from top +/- 10 %	Front Cu Tracking	FR4
		Front Kapton	FR4



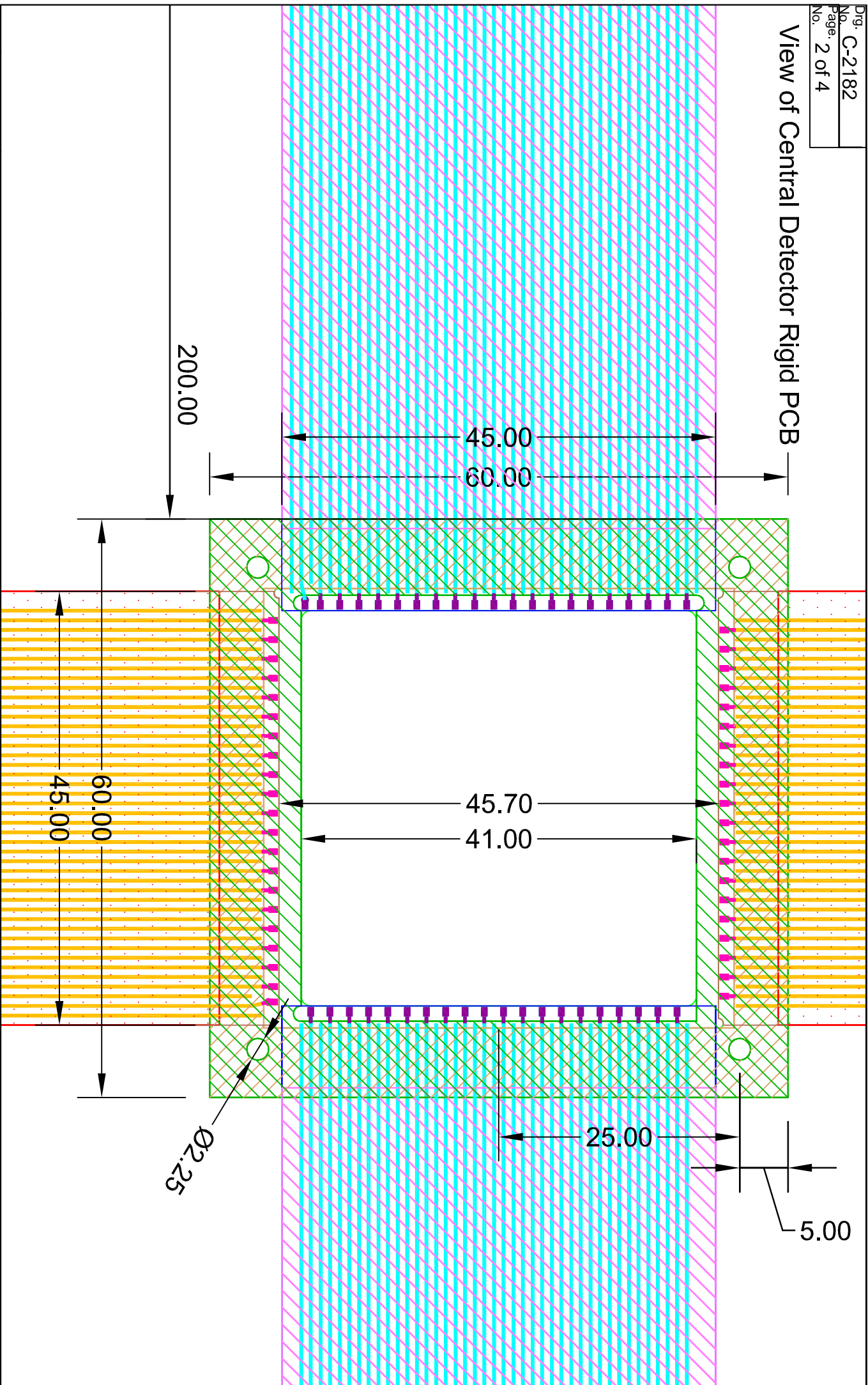
Title:	BB1 Kapton Package Concept. For use with Samtec FTSH-125-01-F-MT Connectors
--------	---

MICRON SEMICONDUCTOR LIMITED

THIS DOCUMENT IS THE PROPERTY OF M.S.L AND IS COMMERCIAL IN CONFIDENCE.  
 graphics@micronsemiconductor.co.uk

Scale: 1:1    Dims In. mm    Dwg. No. C-2182

View of Central Detector Rigid PCB



Drawn, Checked	Date	Tolerances Unless Stated	
N.W	15/06/2010	Package O/D ± 0.1mm	Package Hole Ø ± 0.05mm
S.W		Package Hole Pos'n ± 0.1mm	Material Thickness ± 10 %
Design Approved		Material - ~3.1 mm total thick FR4 PCB material.	Plating - 1 oz soft Au suitable for wire bonding on PCB with rolled annealed Cu on kapton
		Front Spacer- 0.6 mm FR4	Solder Resist Front - N/A
		Rear Spacer- 0.6 mm FR4	Solder Resist Rear - N/A
		Ledge - 1.55 mm deep from top +/- 10 %	

Title:  
**BB1 Kapton Package Concept.**  
 For use with Samtec  
 FTSH-125-01-F-MT Connectors

MICRON SEMICONDUCTOR LIMITED

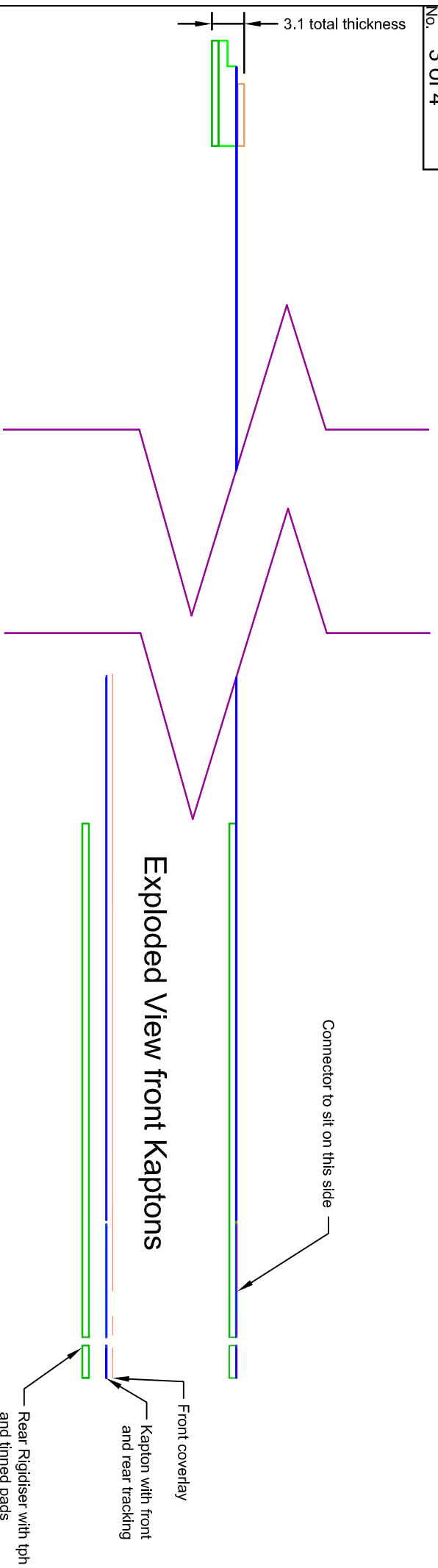
THIS DOCUMENT IS THE PROPERTY OF M.S.L  
 AND IS COMMERCIAL IN CONFIDENCE.  
 graphics@micronsemiconductor.co.uk

Scale: 2:1

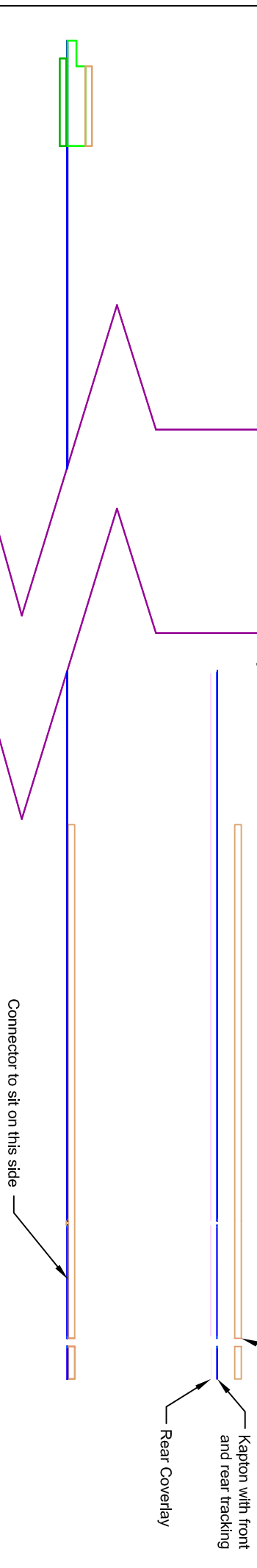
Drawn In: mm

Dwg. No. C-2182

### Side Profile of Front Kaptons



### Side Profile of Rear Kaptons



Drawn, Checked <b>N.W.</b>	Checked <b>S.W.</b>	Date 15/06/2010	Tolerances Unless Stated Package O/D $\pm 0.1$ mm Package Hole $\varnothing \pm 0.05$ mm Package Hole Pos'n $\pm 0.1$ mm Material Thickness $\pm 10$ %	Material - ~3.1 mm total thick FR4 PCB material. Plating - 1oz soft Au suitable for wire bonding on PCB with rolled annealed Cu on kapton. Front Spacer- 0.6 mm FR4 Rear Spacer- 0.6 mm FR4 Ledge - 1.55 mm deep from top +/- 10 %
-------------------------------	------------------------	--------------------	--	--

Title:  
**BB1 Kapton Package Concept.**  
 For use with Samtec  
 FTSH-125-01-F-MT Connectors

**MICRON SEMICONDUCTOR LIMITED**  
 THIS DOCUMENT IS THE PROPERTY OF M.S.L  
 AND IS COMMERCIAL IN CONFIDENCE.  
 graphics@micronsemiconductor.co.uk  
 Scale 2:1  
 Dims In. mm  
 Drg. No. C-2182

**Detector Rigid Thickness**

(The thicknesses listed do not apply to the whole region of the detector rigid, but have assumed that the manufacturer will increase the pre-preg layers in arcs to prevent buckling of the package build. Therefore there has been an over approximation of the total thickness.)

Front Spacer	600 um
Pre-preg	25 um
Front Coverlay	25 um
Pre-Preg	25 um
Front Kapton	50 um
Tracking	25 um
Pre-Preg	1600 um
P/CB	25 um
Pre-preg	25 um
Rear Kapton	50 um
Tracking	25 um
Pre-Preg	25 um
Rear Coverlay	25 um
Pre-Preg	25 um
Rear Spacer	600 um
<b>TOTAL</b>	<b>3100 um</b>

**Front Side Flexi Thickness**

Front Coverlay	25 um
Pre-Preg	25 um
Tracking	33 um
Front Kapton	50 um
Tracking	33 um
=====	
Total	166 um
(including connector rigidiser above plus;)	
Pre-Preg	25 um
Rear Spacer	600 um
Rear Spacer Rear Trim	35 um
=====	
TOTAL	826 um

**Rear Side Flexi Thickness**

Tracking	33 um
Front Kapton	50 um
Tracking	33 um
Pre-Preg	25 um
Rear Coverlay	25 um
=====	
Total	166 um
(including connector rigidiser above plus;)	
Pre-Preg	25 um
Front Spacer	600 um
Front Spacer Front Trim	35 um
=====	
TOTAL	826 um

Drawn, Checked

N.W. S.W.

Design Approved

Date

15/06/2010

Tolerances Unless Stated

Material - ~3.1 mm total thick FR4 PCB material.

Title:

**BB1 Kapton Package Concept.**  
**For use with Samtec**  
**FTSH-125-01-F-MT Connectors**

Package O/D ± 0.1mm  
 Package Hole Ø ± 0.05mm  
 Package Hole Pos'n ± 0.1mm  
 Material Thickness ± 10 %

Plating - 1oz soft Au suitable for wire bonding on PCB with rolled annealed Cu on kapton  
 Front Spacer- 0.6 mm FR4  
 Rear Spacer- 0.6 mm FR4  
 Solder Resist Front - N/A  
 Solder Resist Rear - N/A

Ledge - 1.55 mm deep from top +/- 10 %

MICRON SEMICONDUCTOR LIMITED



THIS DOCUMENT IS THE PROPERTY OF M.S.L  
 AND IS COMMERCIAL IN CONFIDENCE.  
 graphics@micronsemiconductor.co.uk



Scale 2:1

Dims In. mm

Dwg. No. C-2182